



Statement of Materials, Construction

LEAD-FREE -- 16L-SOICN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.05244	Cu	7440-50-8	0.05098	32.78993	97.21
				Fe	7439-89-6	0.00123	0.79265	2.35
				Pb	7439-92-1	0.00002	0.01012	0.03
				P	7723-14-0	0.00004	0.02783	0.08
				Ag (plating)	7440-22-4	0.00010	0.06746	0.20
				Zn	7440-66-6	0.00007	0.04385	0.13
2	Die	Silicon Chip	0.00357	Si	7440-21-3	0.00355	2.28478	99.50
3	Die Attach Material	Conductive Epoxy	0.00112	Epoxy Resin	Proprietary	0.00017	0.10806	15.00
				Ag	7440-22-4	0.00088	0.56911	79.00
				Aromatic Amine	Proprietary	0.00007	0.04322	6.00
4	Wire	Gold	0.00051	Au	7440-57-5	0.00051	0.32800	99.99
5	Lead Finish	Tin	0.00292	Sn	7440-31-5	0.00292	1.87818	100
6	Encapsulation	Epoxy Resin	0.09491	Fused Silica	60676-86-0	0.07612	48.95981	80.20
				Epoxy Resin	29690-82-2	0.00949	6.10471	10.00
				Carbon Black	1333-86-4	0.00028	0.18314	0.30
				Brominated Epoxy Resin	68541-56-0	0.00237	1.52618	2.50
				Phenol Resin	9003-35-4	0.00475	3.05236	5.00
				Antimony Trioxide	1309-64-4	0.00190	1.22094	2.00
Total Package Weight			0.15547					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%